Materials Declaration Form

IPC	1752	Version	2
Form Type *	Distribute		
Sectionals *	Material Info	Subsectionals *	A-D
	Manufacturing Info		* : Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2014-06-12
Contact Name *	Refer to " Supplier Comment" section	Contact Title	Refer to " Supplier Comment" section
Contact Phone *	Refer to " Supplier Comment" section	Contact Email *	Refer to " Supplier Comment" section
Authorized Representative *	Laurent TOSI	Representative Title	MMS MD CHAMPION
Representative Phone *	33 442 685 795	Representative Email *	laurent.tosi@st.com
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/online_tech_support.html		

Uncertainty Statement

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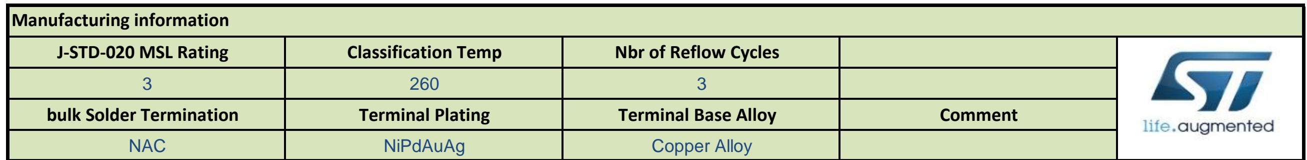
Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	**Mfr Item Name**	**Version**	**Mfr Site**	**Date**
STM32F101VCT6	YE1L*414XXXX	A	9994	2014-03-07
	Amount	**UoM**	**Unit type**	**ST ECOPACK Grade**
	681.44	mg	Each	ECOPACK® 2



Manufacturing information				
J-STD-020 MSL Rating	**Classification Temp**	**Nbr of Reflow Cycles**		life.augmented
3	260	3		
bulk Solder Termination	**Terminal Plating**	**Terminal Base Alloy**	**Comment**	
NAC	NiPdAuAg	Copper Alloy		

Package Designator	**Size**	**Nbr of instances**	**Shape**	
QFP	14x14x1.4	100	L bend	
Comment	Package: LQFP 100L 14x14x1.4			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	**Response**
Product(s) meets EU RoHS requirement without any exemptions	**true**
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false

Exemption Id.	**Description**

QueryList : REACH-16th December 2013				
Query				**Response**
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				**true**
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	YE1L*414XXXX					
Homogeneous Material	**Material Group**	Mass	**UoM**	**Level**	**Substance Category**	**Substance**	**CAS**	**Exempt**	**Mass**	**UoM**	**Concentration in homogeneous material (ppm)**	**Concentration in product (ppm)**
die (s)	Other inorganic materials	18.088	mg	supplier	die	Silicon (Si)	7440-21-3		17.500	mg	967492	25681
die (s)				supplier	metallization	Aluminium (Al)	7429-90-5		0.051	mg	2820	75
die (s)				supplier	metallization	Copper (Cu)	7440-50-8		0.051	mg	2820	75
die (s)				supplier	metallization	Titanium (Ti)	7440-32-6		0.106	mg	5860	156
die (s)				supplier	metallization	Tungsten (W)	7440-33-7		0.021	mg	1161	31
die (s)				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.034	mg	1880	50
die (s)				supplier	passivation	Indium Tin oxide (In203:SnO2)	50926-11-9		0.325	mg	17968	477
Die Attach	Other inorganic materials	3.240	mg	supplier	Glue	Acrylic resins	Trade secret		0.486	mg	150000	713
Die Attach				supplier	Glue	Resin	Trade secret		0.081	mg	25000	119
Die Attach				supplier	Glue	Silver (Ag)	7440-22-4		2.592	mg	800000	3804
Die Attach				supplier	Glue	Treated silica	96-48-0		0.081	mg	25000	119
Leadframe	Other inorganic materials	144.731	mg	supplier	Alloy	Copper (Cu)	7440-50-8		136.684	mg	944400	200581
Leadframe				supplier	Alloy	Iron (Fe)	7439-89-6		3.294	mg	22759	4834
Leadframe				supplier	Alloy	Phosphorous (P)	7723-14-0		0.042	mg	290	62
Leadframe				supplier	Alloy	Zinc (Zn)	7440-66-6		0.168	mg	1161	247
Leadframe				supplier	Coating	Nickel (Ni)	7440-02-0		4.431	mg	30615	6502
Leadframe				supplier	Coating	Palladium (Pd)	7440-05-3		0.094	mg	649	138
Leadframe				supplier	Coating	Gold(Au)	7440-57-5		0.009	mg	62	13
Leadframe				supplier	Coating	Silver(Ag)	7440-22-4		0.009	mg	62	13
Encapsulation	Other inorganic materials	513.352	mg	supplier	Molding compound	Epoxy Resin (Proprietary)	Proprietary		15.388	mg	29976	22582
Encapsulation				supplier	Molding compound	Phenol Resin (Proprietary)	Proprietary		15.388	mg	29976	22582
Encapsulation				supplier	Molding compound	Fused Silica (SiO2)	60676-86-0		454.364	mg	885092	666770
Encapsulation				supplier	Molding compound	Carbon Black	1333-86-4		2.565	mg	4997	3764
Encapsulation				supplier	Molding compound	Metal Hydroxide	Proprietary		25.647	mg	49960	37636
Wire	Other inorganic materials	1.534	mg	supplier	Wire	Gold (Au)	7440-57-5		1.519	mg	990222	2229
Wire				supplier	Wire	Palladium (Pd)	7440-05-3		0.015	mg	9778	22
Finishing	Other inorganic materials	0.495	mg	supplier	Connection coating	Nickel (Ni)	7440-02-0		0.437	mg	882828	641
Finishing				supplier	Connection coating	Palladium (Pd)	7440-05-3		0.026	mg	52525	38
Finishing				supplier	Connection coating	Gold(Au)	7440-57-5		0.016	mg	32323	23
Finishing				supplier	Connection coating	Silver(Ag)	7440-22-4		0.016	mg	32323	23